



DO218 Rectifier

Material Content Declaration					
Material name	Substance name e.g. Copper (Cu), Gold (Au)	CAS no., if known	Substance mass (mg)	% OF Weight (%)	ppm Of Total Weight
Lead Frame 87.55%	Copper (Cu)	7440-50-8	2390.960	100	875501.7
	Total		2390.96		
Solder Wafer 1.46%	Lead (Pb)	7439-92-1	36.96	92.4	13,533.7
	Tin (Sn)	7440-31-5	2.08	5.2	761.6
	Silver (Ag)	7440-22-4	0.96	2.4	351.5
	Total		40		
Chip 0.73%	Silicon (Si)	7440-21-3	19.08	95.4	6,986.6
	Lead (Pb)	7439-92-1	0.92	4.6	336.9
	Total		20		
Molding 9.89%	Quartz(SiO2)	14808-60-7	202.5	75	74,149.7
	formaldehyde,polymer with(chloromethy)oxirane and 2-methylphenol	29690-82-2	54	20	19,773.3
	Antimony trioxide	1309-64-4	13.5	5	4,943.3
	Total		270		
Plating 0.37%	Tin (Sn)	7440-31-5	10	100	3,661.7
	Total		10		
	Total mass (mg)		2730.96		